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zeta potential of said inorganic particles are of opposite signs, and said polymer particles and said inorganic particles are electrostatically bonded to form composite particles, and a plurality of said inorganic particles are attached to a surface of each of said polymer particles, and a ratio (Sp/Si) of a mean particle size of said polymer particles (Sp) and a mean particle size of said inorganic particles (Si) is from 1 to 40.

58. (Amended) An aqueous dispersion for chemical mechanical polishing used in the manufacture of semiconductor devices, said dispersion comprising polymer particles, inorganic particles and water, wherein the zeta potential of said polymer particles and the zeta potential of said inorganic particles are of opposite signs, said polymer particles and said inorganic particles are electrostatically bonded to form composite particles, and a plurality of said inorganic particles are attached to a surface of each of said polymer particles, and a ratio (Sp/Si) of a mean particle size of said polymer particles (Sp) and a mean particle size of said inorganic particles (Si) is from 1 to 40, said composite particles are obtained after ultrasonic irradiation treatment or mechanical shear stress treatment with a homogenizer, and a mean particle size of said composite particles is not greater than $1\mu\text{m}$.

REMARKS

Claims 40-60 are active in the present application. Claims 44-60 are currently under prosecution. Claims 40-43 are non-elected claims. Independent Claims 44 and 58 have been amended for clarity. The amended claims state that a plurality of inorganic particles are attached to the surface of each polymer particle. Support for the amendment is found in the Drawings, for example see Figure 2, Figure 12 or Figure 13. No new matter is added.